

JEAN-151-SAC305-T4

Rev: 19.11

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Language	English
SDS	950631



SUMMARY

Pb-free - Halide-free - Premium latest technology No-Clean, Fine Pitch solder paste

PASTE	JEAN-151-SAC305-T4
PROCESS	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	8
Industrial electronics	9
Hi-Rel electronics (automotive)	9

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	8
Pb-free process N2	9
Vapor phase process	8
Shiny joint appearance	8
Cosmetic cleanliness	8
ICCT compatible	N/A
Conformal coating	N/A

Legend	
<i>Especially made for this purpose</i>	9 - 10
<i>Generally qualified for this purpose</i>	7 - 8
<i>Generally usable, but not the best choice</i>	5 - 6
<i>Generally not usable for this purpose</i>	3 - 4
<i>Wrong choice</i>	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

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CLASSIFICATION

DIN-EN-ISO-9454-1: 2016	1122
IPC-J-STD-004-A: 2004	ROLO
IPC-J-STD-005: 1995 (Powder)	T4
Particle size	[µm] 20-38

PROPERTIES

Flux code	JEAN-151	
Alloy Code	SAC305	
Alloy composition	Sn96.5Ag3Cu0.5	
Liquidus	[°C]	219
Solidus	[°C]	217
Recommended peak temp.	[°C]	232-260
Acid number	[mg KOH/g]	123
Flux	[% w/w]	11.3
Residues	Colorless	
Tackiness Malcom TK1	IPC-TM-650 2.4.44	[gf] @ 0h 35

TEST REPORTS

IPC/ANSI-J-STD-005	Compliant	
Certificate of Compliance	Website	
RoHS Compliant	Available	
Application Note	EN/DE	
Copper Mirror	IPC-TM-650 2.3.32	Pass
Halides	IPC-TM-650 2.3.33	[Silver Chromate] Pass
Halide	IPC-TM-650 2.3.35.1	[Fluoride by Spot] Pass
Copper Corrosion	IPC-TM-650 2.6.15	Pass
SIR	IPC-TM-650 2.6.3.3	Pass
ECM	IPC-TM-650 2.6.14.1	Pass

PACKAGING AND STORAGE

Packaging jar	PP [g]	500
Packaging cartridge	HDPE [g]	650
Packaging cartridge	HDPE [g]	1300
Packaging Cassette Pro-Flow	[g]	800
Minimum shelf-life in months	4-10 °C	12